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Vishay General Semiconductor

# **Surface-Mount Glass Passivated Rectifier**



Cathode O Anode

# LINKS TO ADDITIONAL RESOURCES



PRIMARY CHARACTERISTICS				
I <sub>F(AV)</sub>	3 A			
V <sub>RRM</sub> 400 V, 600 V				
I <sub>FSM</sub> 50 A				
I <sub>R</sub>	10 µA			
V <sub>F</sub> at I <sub>F</sub> = 3 A (125 °C)	0.9			
T <sub>J</sub> max.	175 °C			
Package	SlimSMA (DO-221AC)			
Circuit configuration	Single			

## FEATURES

- Very low profile typical height of 0.95 mm
- · Ideal for automated placement
- · Glass passivated pellet chip junction
- Low forward voltage drop
- · Low leakage current
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified available
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

## **TYPICAL APPLICATIONS**

For use in general purpose rectification of power supplies, inverters, converters and freewheeling diodes for consumer, and industrial applications

### **MECHANICAL DATA**

Case: SlimSMA (DO-221AC)

Molding compound meets UL 94 V-0 flammability rating Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and AEC-Q101 qualified

**Terminals:** matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 and HM3 suffix meet JESD 201 class 2 whisker test

Polarity: color band denotes cathode end

<b>MAXIMUM RATINGS</b> ( $T_A = 25 \text{ °C}$ unless otherwise noted)					
PARAMETER	SYMBOL	S3AFG	S3AFJ	UNIT	
Device marking code		3G	3J		
Maximum repetitive peak reverse voltage	V <sub>RRM</sub>	400	600	V	
Maximum average forward rectified current	I <sub>F(AV)</sub> <sup>(1)</sup>	3		A	
	I <sub>F(AV)</sub> <sup>(2)</sup>	1.3		А	
Peak forward surge current 10 ms single half sine-wave	I <sub>FSM</sub>	50		А	
Operating junction and storage temperature range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +175		°C	

Notes

<sup>(1)</sup> Mounted on 20 mm x 20 mm pad areas, 2 oz. FR4 PCB

<sup>(2)</sup> Free air, mounted on recommended copper pad area





S3AFG, S3AFJ



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<b>ELECTRICAL CHARACTERISTICS</b> ( $T_J = 25 \text{ °C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS		SYMBOL	TYP.	MAX.	UNIT
Instantaneous forward voltage	I <sub>F</sub> = 1.5 A	T <sub>J</sub> = 25 °C	- V <sub>F</sub> <sup>(1)</sup>	0.93	-	V
	I <sub>F</sub> = 3.0 A			1	1.1	
	I <sub>F</sub> = 1.5 A	– T <sub>J</sub> = 125 °C		0.81	-	
	I <sub>F</sub> = 3.0 A			0.9	-	
Max. reverse current	Dated V/	T <sub>J</sub> = 25 °C	I <sub>R</sub> (2)	-	10	μA
	Rated V <sub>R</sub>	T <sub>J</sub> = 125 °C		-	100	
Typical reverse recovery time	$I_F = 0.5 \text{ A}, I_R = 1.0 \text{ A}, I_{rr} = 0.25 \text{ A}$		t <sub>rr</sub>	2.7	-	μs
Typical junction capacitance	4.0 V, 1 MHz		CJ	28	-	pF

#### Notes

<sup>(1)</sup> Pulse test: 300 µs pulse width, 1 % duty cycle

<sup>(2)</sup> Pulse test: Pulse width  $\leq$  40 ms

<b>THERMAL CHARACTERISTICS</b> ( $T_A = 25$ °C unless otherwise specified)				
PARAMETER	SYMBOL	S3AFG	S3AFJ	UNIT
Typical thermal resistance	R <sub>0JA</sub> (1)(2)	130		°C/W
	R <sub>θJM</sub> <sup>(3)</sup>	7.3		

#### Notes

 $^{(1)}$  The heat generated must be less than thermal conductivity from junction-to-ambient: dP<sub>D</sub>/dT<sub>J</sub> < 1/R<sub>0JA</sub>

<sup>(2)</sup> Thermal resistance junction-to-ambient to follow JEDEC<sup>®</sup> 51-2A, device mounted on FR4 PCB, 2 oz., standard footprint

<sup>(3)</sup> Thermal resistance junction-to-mount to follow JEDEC<sup>®</sup> 51-14, transient dual interface test method (TDIM)

ORDERING INFORMATION (Example)					
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE	
S3AFJ-M3/I	0.0307	I	14 000	13" diameter plastic tape and reel	
S3AFJHM3/I <sup>(1)</sup>	0.0307	I	14 000	13" diameter plastic tape and reel	

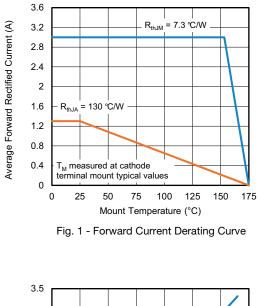
#### Note

(1) AEC-Q101 qualified



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# **RATINGS AND CHARACTERISTICS CURVES** ( $T_A = 25$ °C unless otherwise specified)



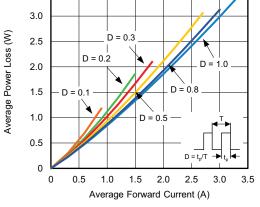
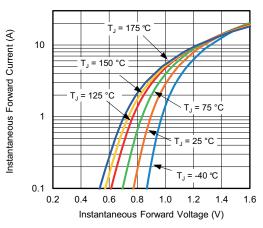
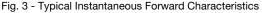


Fig. 2 - Forward Power Loss Characteristics





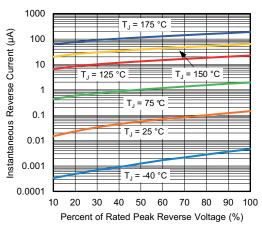
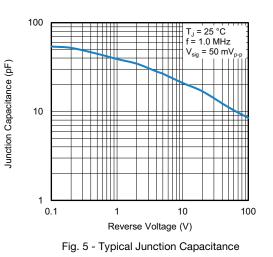


Fig. 4 - Typical Reverse Leakage Characteristics Per Diode



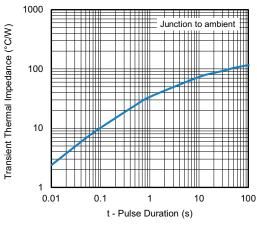


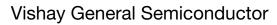
Fig. 6 - Typical Transient Thermal Impedance

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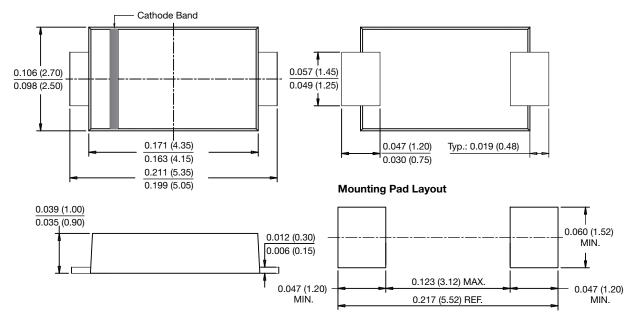
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## PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

SlimSMA (DO-221AC)





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